

Statement of Compliance

Requested Part

TE Internal Number:6-520314-2Product Description:TRIOMATE ASSY H 12P L=2.54LDFRPart Status:ActiveMil-Spec Certified:NoEU RoHS Directive 2011/65/EUCompliantThis declaration covers EU Directive 2011/65/EU incl. Delegated Directive:Compliant2000/53/ECCompliantEU ELV Directive:Compliant2000/53/ECSolder Process Capability CovKer Bur Beach Regulation:Current ECHA Candidate List: JAN 2023 (233) Des not contain REACH SVHCKer Bur Beach Regulation:No to Low Halogen - contains Br or Cl > 900 ppm.Ker Balogen Content:MD=6-520314-2 MD=6-520314-2	12 June 2023	6-5203 ⁻	14-2	(Part 1 of 1)	
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2000/53/ECChina RoHS 2 Directive: MIIT Order No 32, 2016Image: Solution of the state of	This declaration covers EU Directive 2011/65/EU incl. Delegated Directive 2015/863/EU.				
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 (EC) No. 1907/2006 Candidate List Declared Against: JAN 2023 (233) Does not contain REACH SVHC Halogen Content: Not Low Halogen - contains Br or Cl > 900 ppm. Solder Process Capability Code: Wave solder capable to 265°C Material Declarations: MD_6-520314-2 			No Restricted Materials Above	Threshold	
Solder Process Capability Code: Wave solder capable to 265°C Material Declarations: MD_6-520314-2		-	Candidate List Declared Against: JA		
Material Declarations: MD_6-520314-2		Halogen Content:	Not Low Halogen - contains Br or Cl	> 900 ppm.	
	Solder Process Capability Code:		Wave solder capable to 265°C		
MD_6-520314-2		Material Declarations:	MD_6-520314-2		
			MD_6-520314-2		

TE Connectivity Corporation

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This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change.

The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked.

Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV).

Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: https://echa.europa.eu/guidance-documents/guidance-on-reach

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